

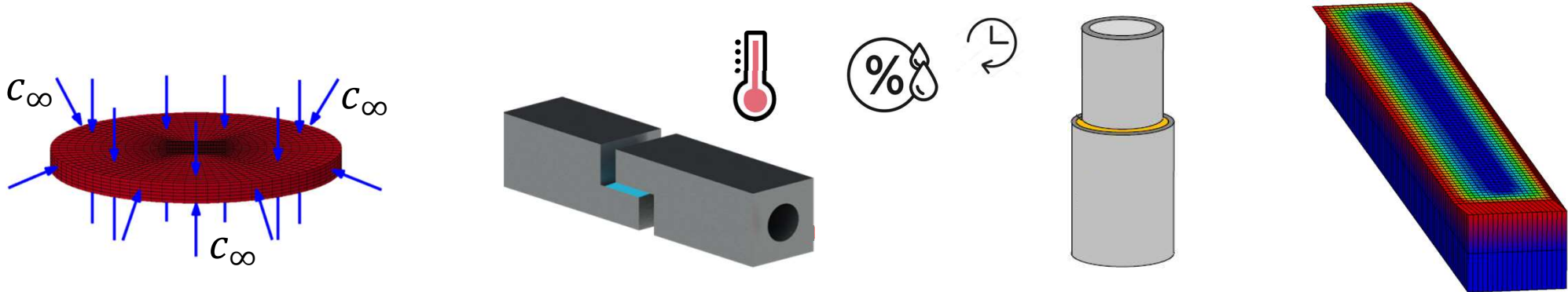
16. LS-DYNA Forum 2022

October 11 - 12, 2022, Bamberg, Germany

Fabian Kötz, Anton Matzenmiller

Method Development: Characterization, Modeling and Simulation of Hygro-Thermo Effects in Thick Layer Adhesives

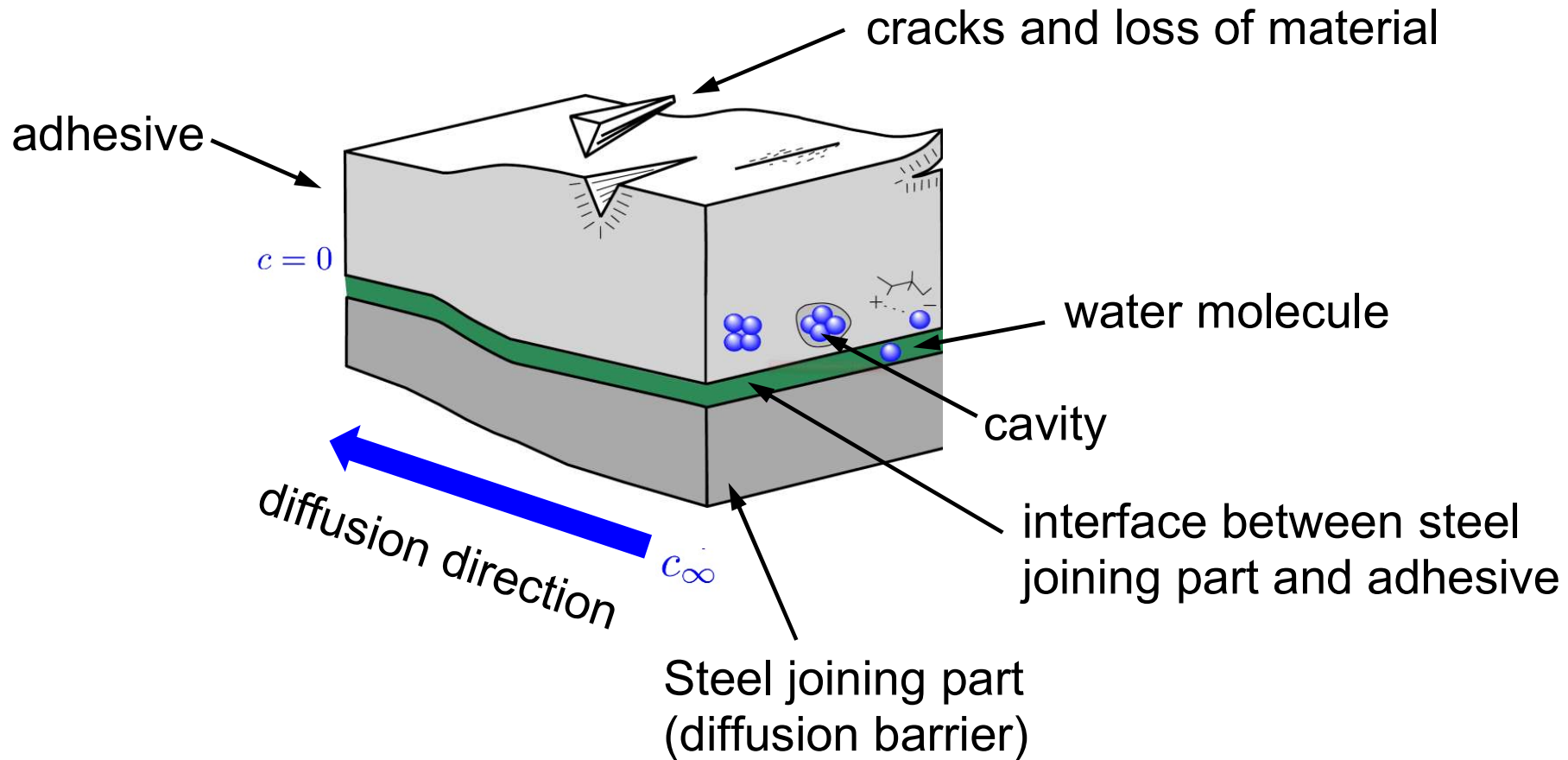
Institute of Mechanics – Department of Mechanical Engineering – University of Kassel, Germany



Agenda

- Motivation
- Moisture simulation with LS-DYNA
- Material model for the adhesive
 - Reversible effects
 - Irreversible damage
- Simulation and validation

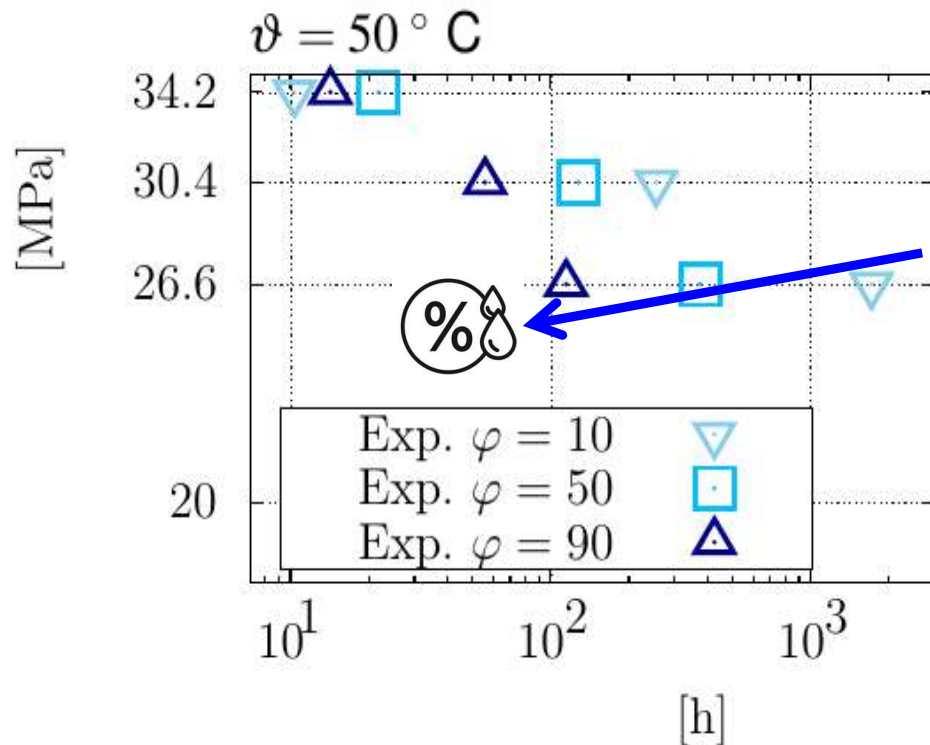
Effects: Water diffusion in adhesive



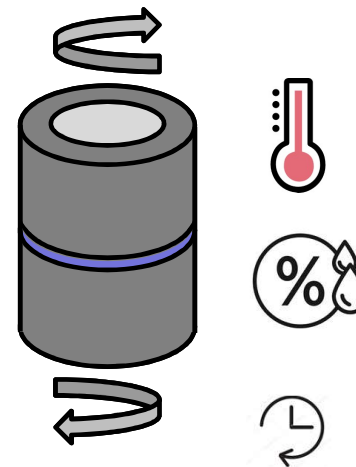
[1] D. A. Bond, P. A. S. (2006). Applied Mechanics Reviews, 59(1-6):249 – 268.

Motivation

Successive degradation of stiffness and strength due to damage resulting from chemical aging



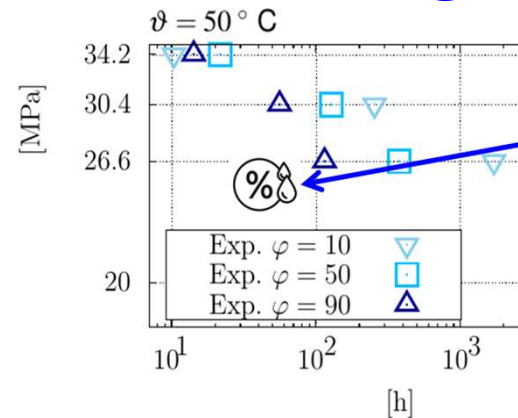
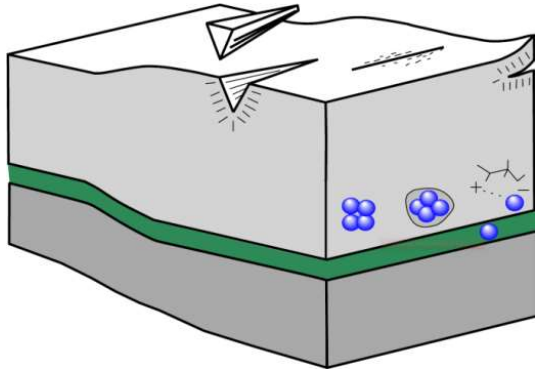
$M = \text{const.}$



→ Significant reduction of lifetime: depending on **humidity**, **temperature** and loading

[1] Bieker, C. (2006). "Methodenentwicklung zur Bestimmung des hydrothermo-mechanischen Langzeitverhaltens von strukturellen Klebverbindungen mit metallischen und mineralischen Untergründen". Schriftenreihe des Instituts für Werkstofftechnik Kassel. Shaker. Dissertation.

Procedure for determining the diffusion properties



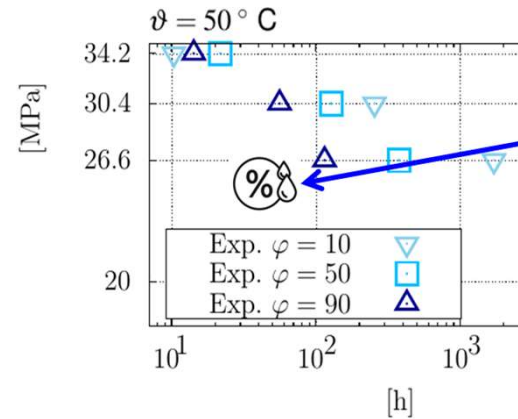
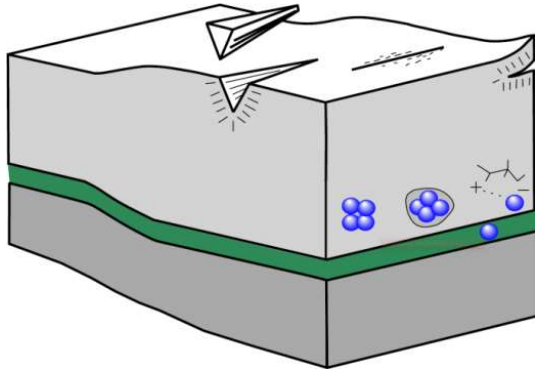
Model development, which describes the **hygro-thermo-mechanical** influences on the service life of the adhesive layer

First step: Description of the diffusion behavior

Second step: Classification into reversible and irreversible damage by water

Third step: Combination with the material model and thermo-mechanical damage

Procedure for determining the diffusion properties



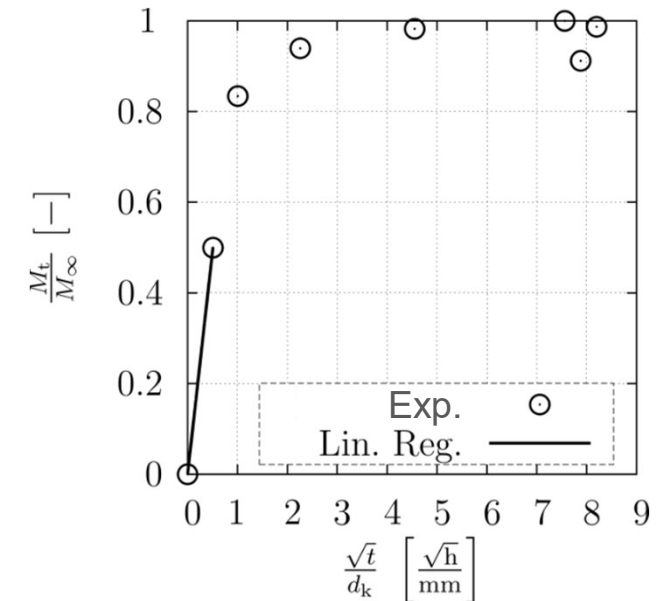
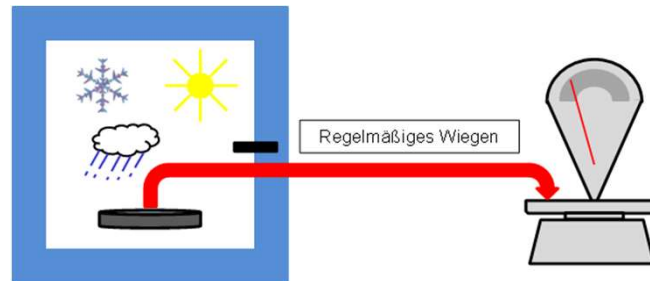
Model development, which describes the **hygro-thermo-mechanical** influences on the service life of the adhesive layer

First step: **Description of the diffusion behaviour**

Modeling moisture absorption

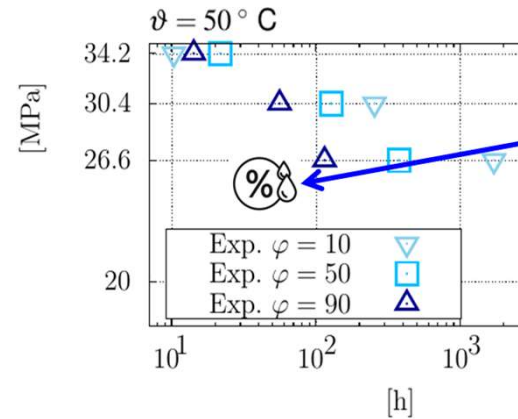
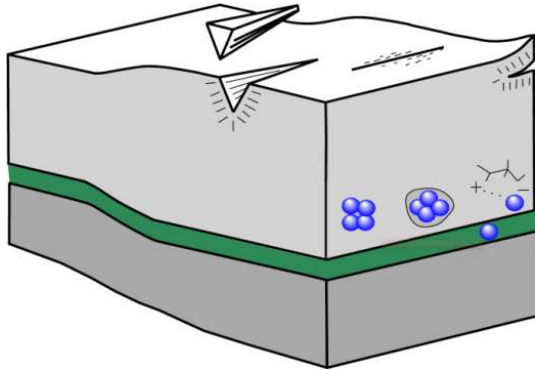


Experimental investigation based on adhesive samples



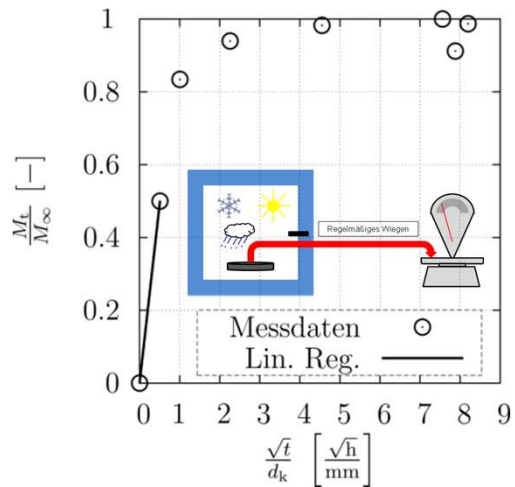
[1] Laboratorium für Werkstoff und Fügetechnik, Paderborn, Prof. Meschut

Procedure for determining the diffusion properties



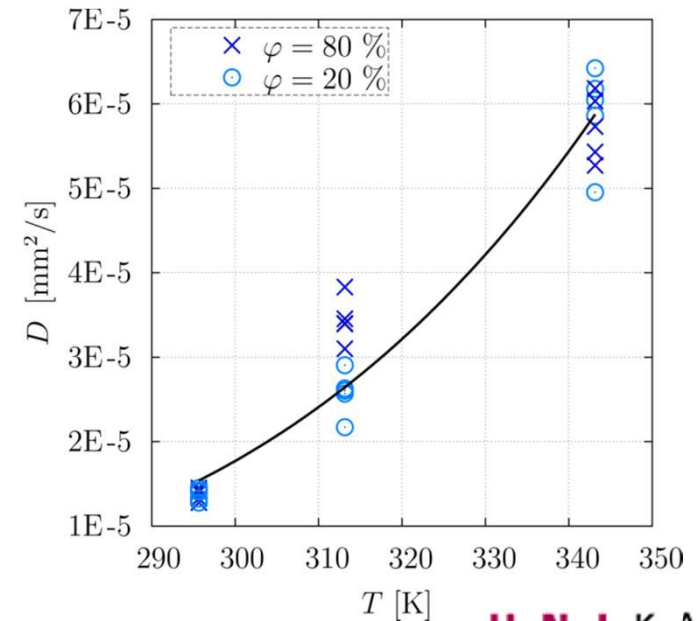
Model development, which describes the **hygro-thermo-mechanical** influences on the service life of the adhesive layer

First step: **Description of the diffusion behaviour**



Diffusion coefficient:

$$D = D_0 \exp \left(D_1 \left(\frac{1}{T_{\text{ref}}} - \frac{1}{T} \right) \right)$$



[1] Crank, The Mathematics of Diffusion, 1975

[2] Laboratorium für Werkstoff und Fügetechnik, Paderborn, Prof. Meschut

[3] Abdel-Wahab et al., Diffusion of Moisture in Adhesively Bonded Joints, 2001

Moisture Simulation with LS-DYNA

LS-DYNA has no **diffusion** solver, therefore the **temperature** solver is used

Diffusion

Thermal conduction

FICK's first law $\mathbf{J} = -D\nabla c$	FOURIERS heat conduction $\mathbf{q} = -k\nabla T$
continuity equation $\frac{\partial c}{\partial t} + \nabla \cdot \mathbf{J} = 0$	heat transfer $\rho C_p \frac{\partial T}{\partial t} + \nabla \cdot \mathbf{q} = 0$
FICK's second law $\frac{\partial c}{\partial t} = D\nabla^2 c$	heat equation $\frac{\partial T}{\partial t} = \frac{k}{\rho C_p} \nabla^2 T$

Moisture Simulation with LS-DYNA

LS-DYNA has no **diffusion** solver, therefore the **temperature** solver is used

Diffusion **Thermal conduction**

<p>FICK's first law $\mathbf{J} = -D\nabla c$</p> <p>continuity equation $\frac{\partial c}{\partial t} + \nabla \cdot \mathbf{J} = 0$</p> <p>FICK's second law $\frac{\partial c}{\partial t} = D\nabla^2 c$</p>	<p>FOURIERS heat conduction $\mathbf{q} = -k\nabla T$</p> <p>heat transfer $\rho C_p \frac{\partial T}{\partial t} + \nabla \cdot \mathbf{q} = 0$</p> <p>heat equation $\frac{\partial T}{\partial t} = \frac{k}{\rho C_p} \nabla^2 T$</p>
<p>concentration c mass flow \mathbf{J} diffusion coefficient D 1 1</p>	<p>temperature T heat flow \mathbf{q} thermal conductivity k specific heat capacity C_p density ρ</p>

The ***THERMAL_SOLVER** of LS-DYNA can be used for the solution of the hygric field problem,

the **diffusion** and **thermal** problems have analogous field equations and boundary conditions

Moisture Simulation with LS-DYNA

LS-DYNA has no **diffusion** solver, therefore the **temperature** solver is used

Diffusion

Thermal conduction

FICK's first law

$$\mathbf{J} = -D\nabla c$$

continuity equation

$$\frac{\partial c}{\partial t} + \nabla \cdot \mathbf{J} = 0$$

FICK's second law

$$\frac{\partial c}{\partial t} = D\nabla^2 c$$

FOURIERS heat conduction

$$\mathbf{q} = -k\nabla T$$

heat transfer

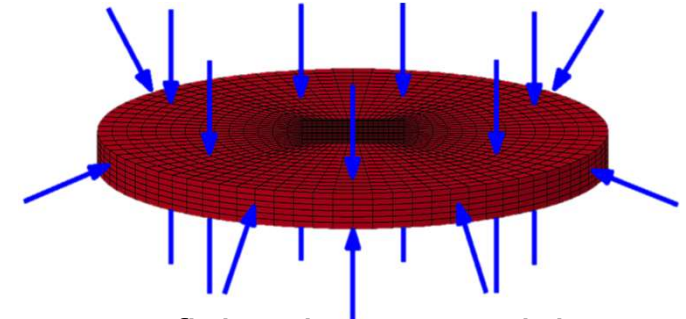
$$\rho C_p \frac{\partial T}{\partial t} + \nabla \cdot \mathbf{q} = 0$$

heat equation

$$\frac{\partial T}{\partial t} = \frac{k}{\rho C_p} \nabla^2 T$$



adhesive sample



finite element model

***BOUNDARY_TEMPERATURE_SET**

***MAT_THERMAL_ISOTROPIC**

concentration c

mass flow \mathbf{J}

diffusion coefficient D

1

1

temperature T

heat flow \mathbf{q}

thermal conductivity k

specific heat capacity C_p

density ρ

Moisture Simulation with LS-DYNA

LS-DYNA has no **diffusion** solver, therefore the **temperature** solver is used

Diffusion

Thermal conduction

FICK's first law

$$\mathbf{J} = -D\nabla c$$

continuity equation

$$\frac{\partial c}{\partial t} + \nabla \cdot \mathbf{J} = 0$$

FICK's second law

$$\frac{\partial c}{\partial t} = D\nabla^2 c$$

FOURIERS heat conduction

$$\mathbf{q} = -k\nabla T$$

heat transfer

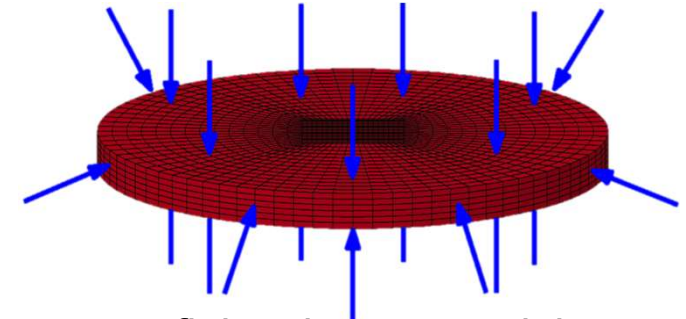
$$\rho C_p \frac{\partial T}{\partial t} + \nabla \cdot \mathbf{q} = 0$$

heat equation

$$\frac{\partial T}{\partial t} = \frac{k}{\rho C_p} \nabla^2 T$$



adhesive sample

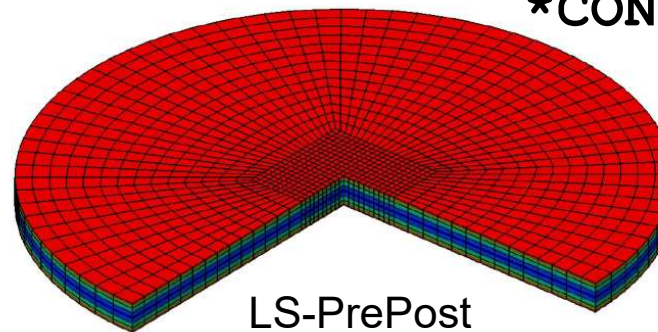


finite element model

***BOUNDARY_TEMPERATURE_SET**

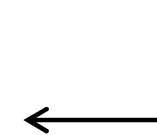
***MAT_THERMAL_ISOTROPIC**

***CONTROL_THERMAL_SOLVER**



LS-PrePost

temperature → concentration



concentration c
mass flow \mathbf{J}
diffusion coefficient D
1
1

temperature T
heat flow \mathbf{q}
thermal conductivity k
specific heat capacity C_p
density ρ

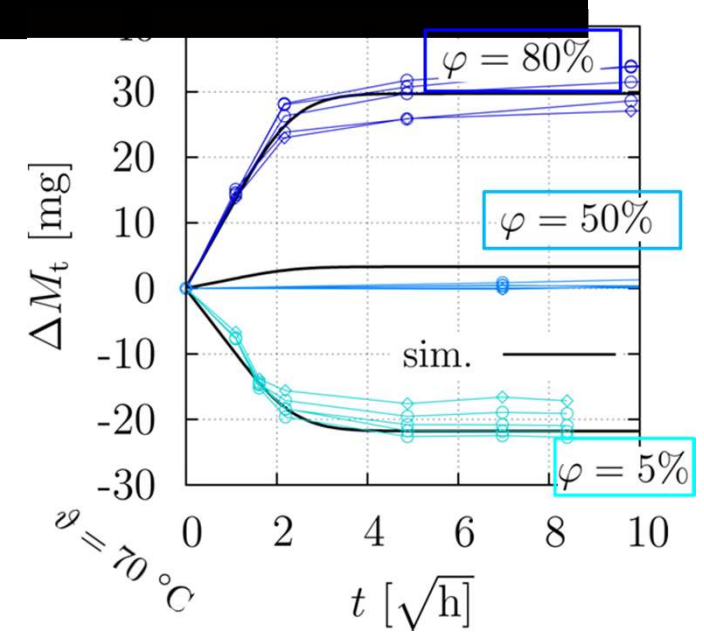
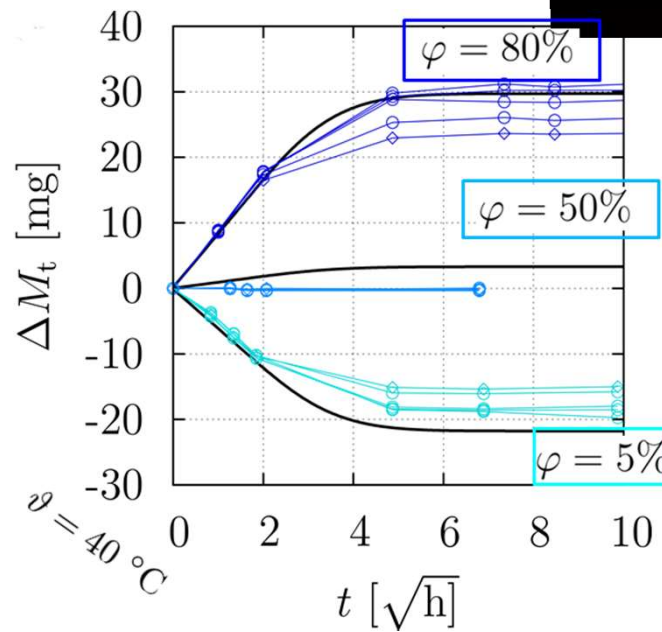
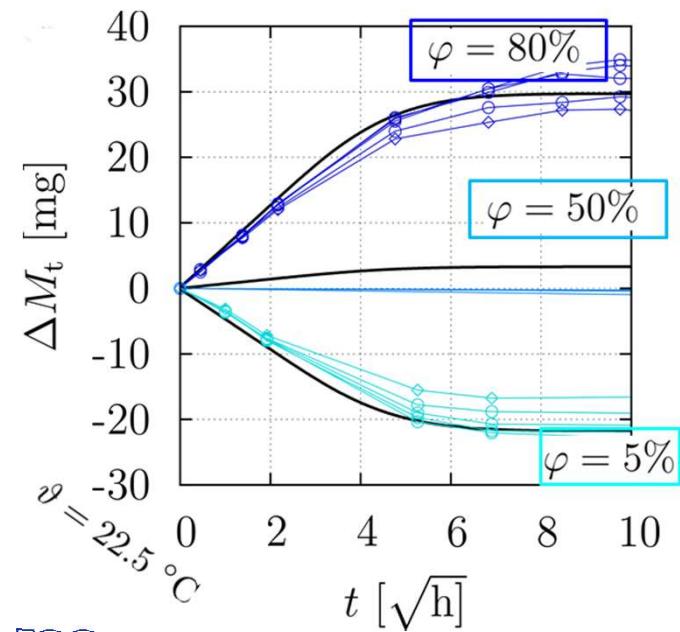
Moisture Simulation with LS-DYNA

Verification of the parameter identification



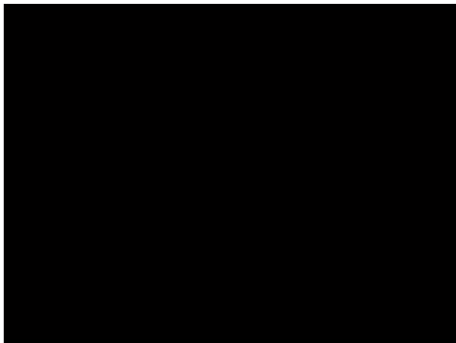
$$M = \underbrace{A \cdot d_k}_{V} \cdot c \quad \swarrow \nearrow T$$

Comparison of experiment and calculation: good agreement

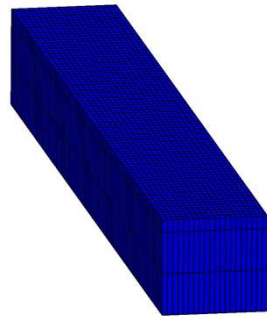


Concentration calculation in different adhesive bonding specimens

Successful simulation of water absorption is used to calculate the concentration in any sample geometries



butt joint specimen



shear specimen

Time = 0
Contours of Temperature
min=0, at node# 1060300
max=0, at node# 1060300



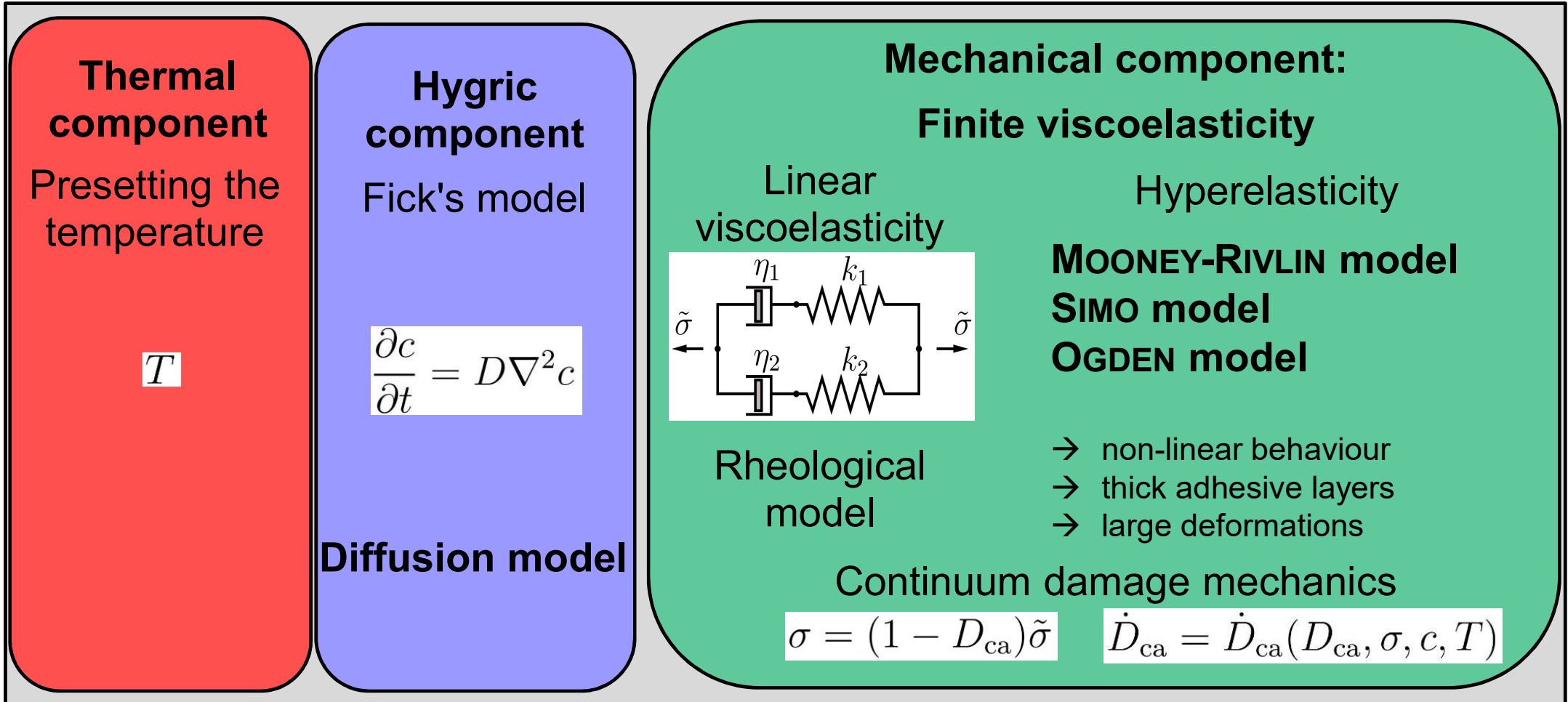
component-like specimen

Concentration used as damage driving variable for calculation of reversible effects and irreversible damage

Agenda

- Motivation
- Moisture simulation with LS-DYNA
- Material model for the adhesive
 - Reversible effects
 - Irreversible damage
- Simulation and validation

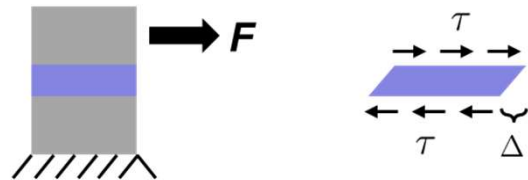
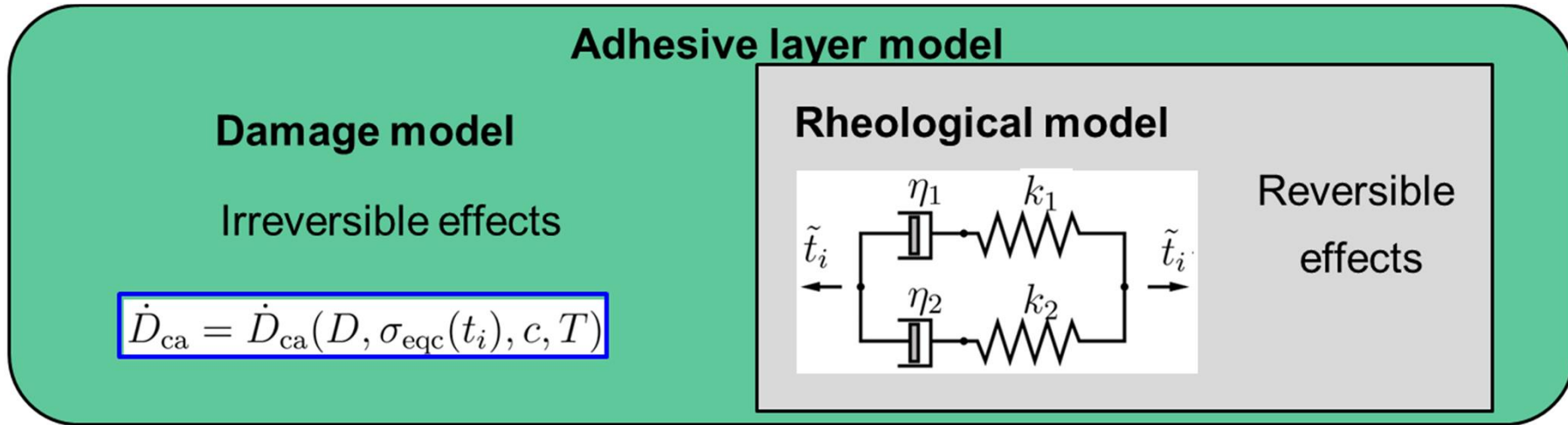
Description of the semi-structural adhesive behaviour under aging



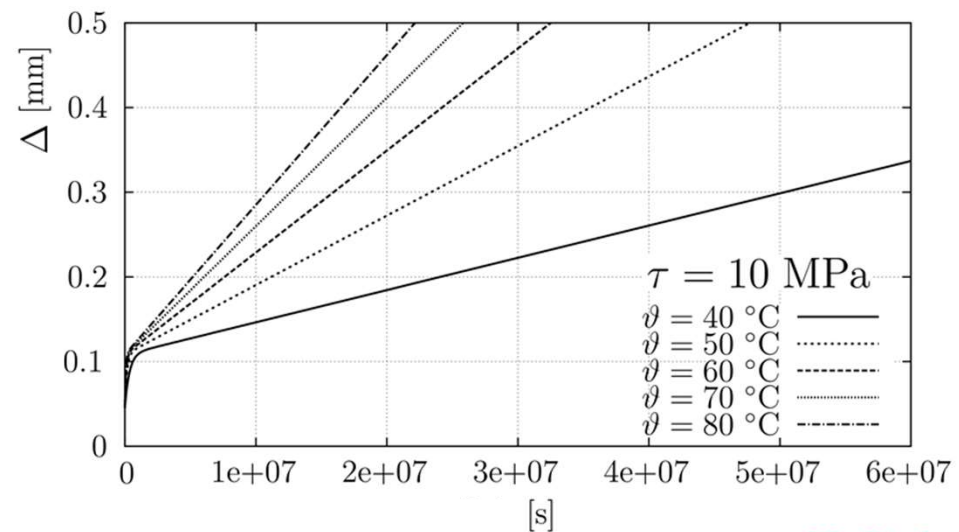
Agenda

- Motivation
- Moisture simulation with LS-DYNA
- Material model for the adhesive
 - Reversible effects
 - Irreversible damage
- Simulation and validation

Reversible effects: Time-concentration-temperature shift

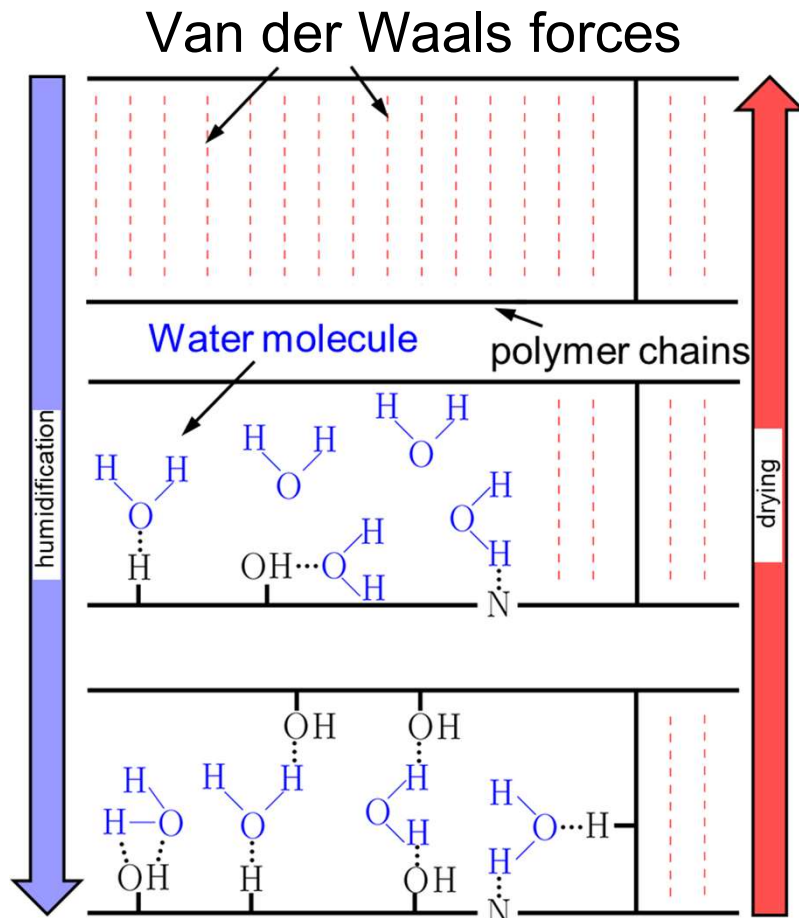


Faster creep / relaxation
at higher temperatures



Concentration as reversible damaging factor

Reversible effect

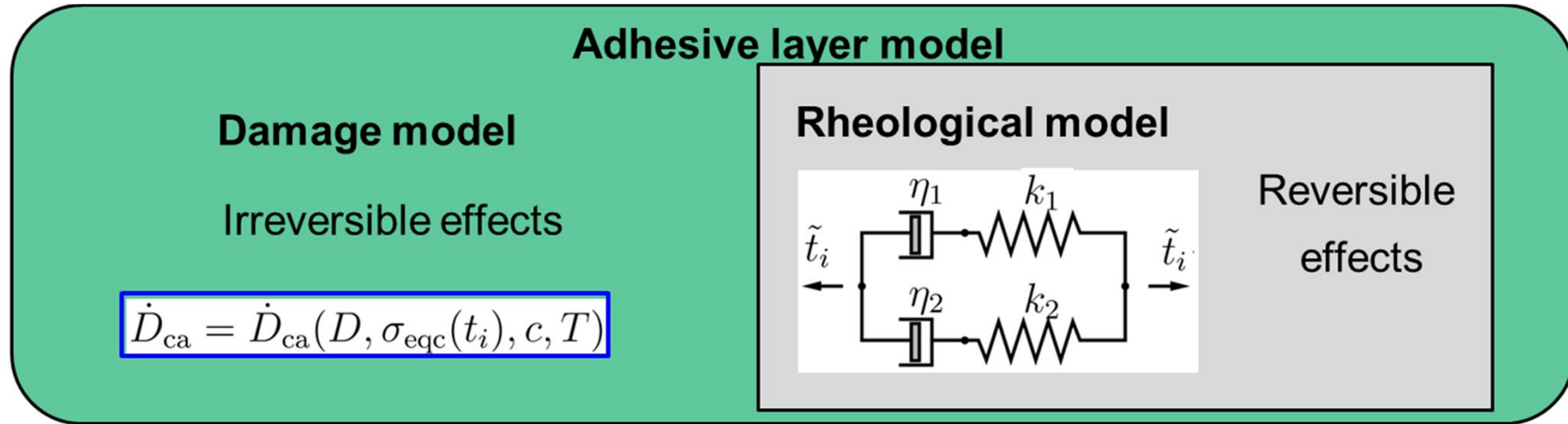


- Water diffuses between polymer chains when moistened and breaks down Van der Waals forces
- Hydrogen bonds can be dissolved again by drying (higher temperature may be necessary).
- Water diffuses out completely during drying
- (thermo-)reversible in the chemical sense [2].

[1] Zhou, J. and Lucas, J. P. (1999). Polymer, 40(20):5505–5512.

[2] Petrie, E. (2005). Epoxy Adhesive Formulations, S. 319

Reversible effects: Time-concentration-temperature shift



Modeling of the reversible effect of temperature and concentration

WIECHERT-/ MAXWELL-Model:
$$R(t - \tau, T) = k_{\infty} + \sum_{i=1}^M k_i \exp\left(-\frac{t - \tau}{a_T(T)\hat{\tau}_i}\right)$$

Time-temperature-shift:
$$a_T(T)$$

Time-concentration-temperature shift:
$$a_{res}(T, c) = a_T(T)a_c(c)$$

Reversible effects: Time-concentration-temperature shift

Time-concentration-temperature shift: $a_{\text{res}}(T, c) = a_T(T)a_c(c)$

Approach for time-
temperature shift
function

$$\log a_T(T) = \frac{-p_{T1}(T - T_{aT})}{p_{T2} + T - T_{aT}} \quad \text{WILLIAMS-LANDEL-FERRY- (WLF-) [1,2]}$$

$$\log a_T(T) = E_A \left(\frac{1}{T} - \frac{1}{T_{aT}} \right) \quad \text{ARRHENIUS [2]}$$

Transfer to time
concentration shift
function

$$\log a_c(c) \stackrel{[3,4]}{=} \frac{-p_{c1}(c - c_{ac})}{p_{c2} + c - c_{ac}}$$

$$\ln a_c(c) \stackrel{[5]}{=} p_{c1} + p_{c2} \left(1 - \exp \left(\frac{c_{ac} - c}{p_{c3}} \right) \right)$$

***usermat**

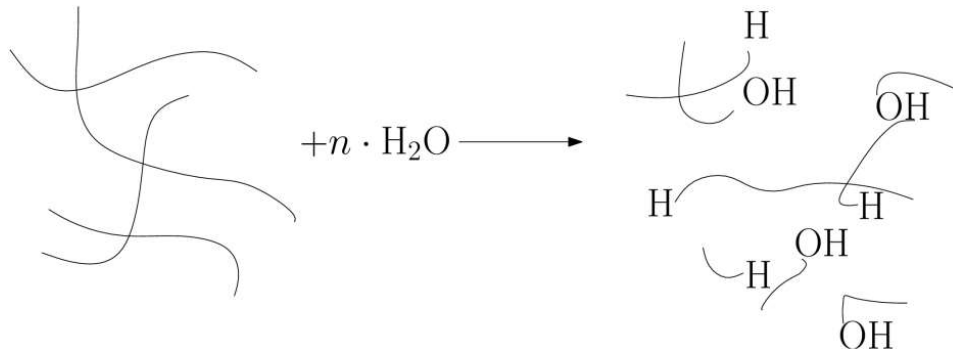
[1] Williams et. Al., 1955 [2] s. FOSTA-Projekt P 1087 [3] Maksimov et. al, 1972 [4] Ma et. al, 2006 [5] Zheng et. al, 2004

Agenda

- Motivation
- Moisture simulation with LS-DYNA
- Material model for the adhesive
 - Reversible effects
 - Irreversible damage
- Simulation and validation

Concentration as irreversible damaging factor

Irreversible effects [2,3]



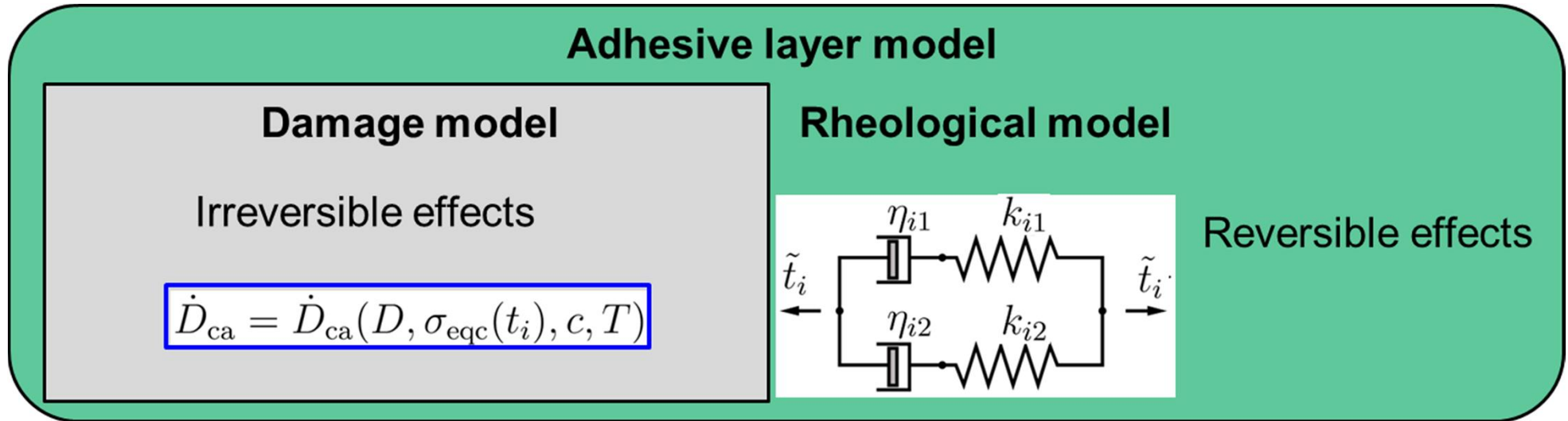
- Breaking of the polymer chains by hydrolysis
- Previously intact chemical bonds in the polymer cannot be restored by drying
- irreversible in the chemical meaning
- Stress reduces activation energy for hydrolysis

[1] Zhou, J. and Lucas, J. P. (1999). Polymer, 40(20):5505–5512.

[2] Petrie, E. (2005). Epoxy Adhesive Formulations, S. 319

[3] Comyn, J. (1997). Adhesion Science, S. 133

Damage model – Differential equation



$$\dot{D}_{ca} = \frac{1}{c_0} \left(\frac{\sigma_{eqc}}{\sigma_{ref}(1 - D_{ca})} \right)^n \exp \left(p_c \left(\frac{1}{T_{refc}} - \frac{1}{T} \right) \right) + B_a(1 - D_{ca}) \left(\frac{c}{c_{\infty,ref}} \right)^l \exp \left(p_a \left(\frac{1}{T_{refa}} - \frac{1}{T} \right) \right)$$

$c_0 = 1 \text{ s}$

\dot{D}_c

Creep damage

Parameter: $\sigma_{ref}, n, T_{refc}, p_c$

\dot{D}_a

Aging damage / hygro damage

Parameter: B_a, l, T_{refa}, p_a

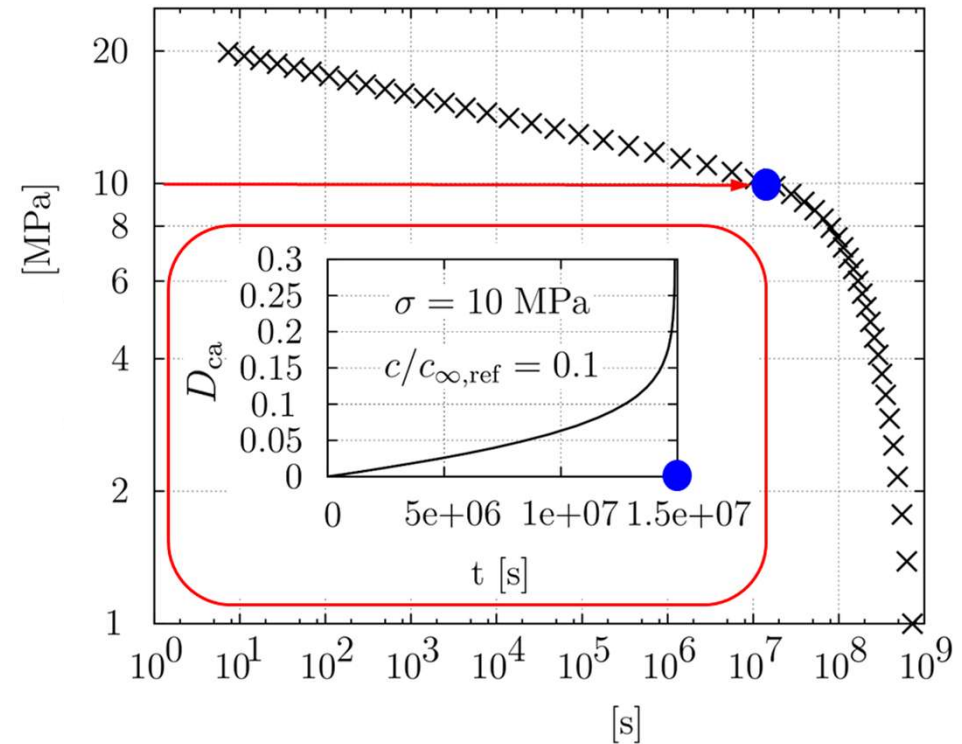
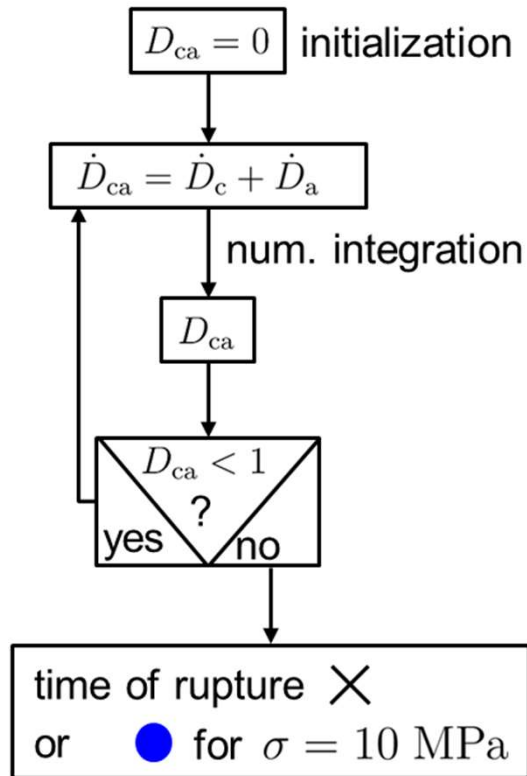


Solution with LS-DYNA: Hygro-thermo-mechanical damage

$$\dot{D}_{ca} = \underbrace{\frac{1}{c_0} \left(\frac{\sigma}{\sigma_{ref}(1 - D_{ca})} \right)^n \exp \left(p_c \left(\frac{1}{T_{refc}} - \frac{1}{T} \right) \right)}_{\dot{D}_c} + \underbrace{B_a(1 - D_{ca}) \frac{c}{c_{\infty,ref}} \exp \left(p_a \left(\frac{1}{T_{refa}} - \frac{1}{T} \right) \right)}_{\dot{D}_a}$$

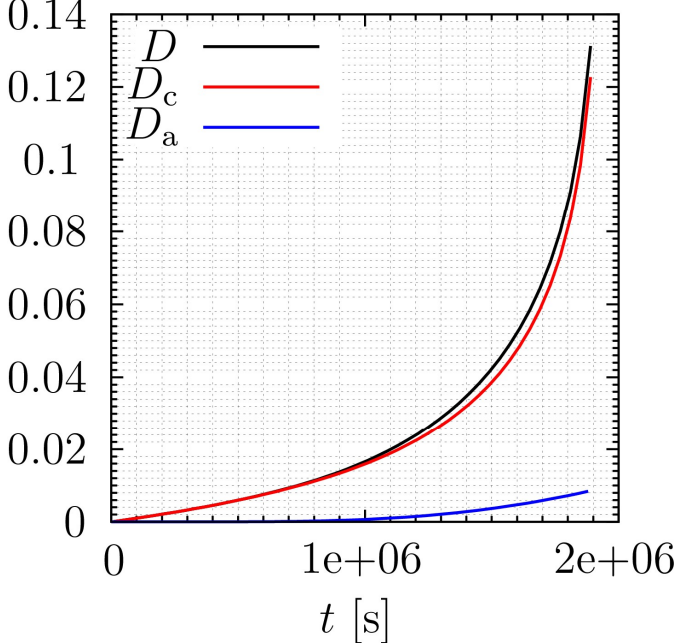
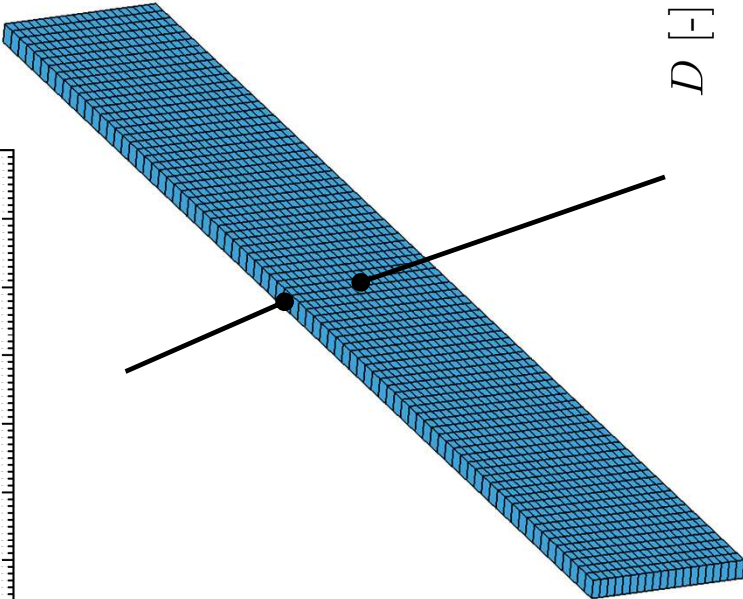
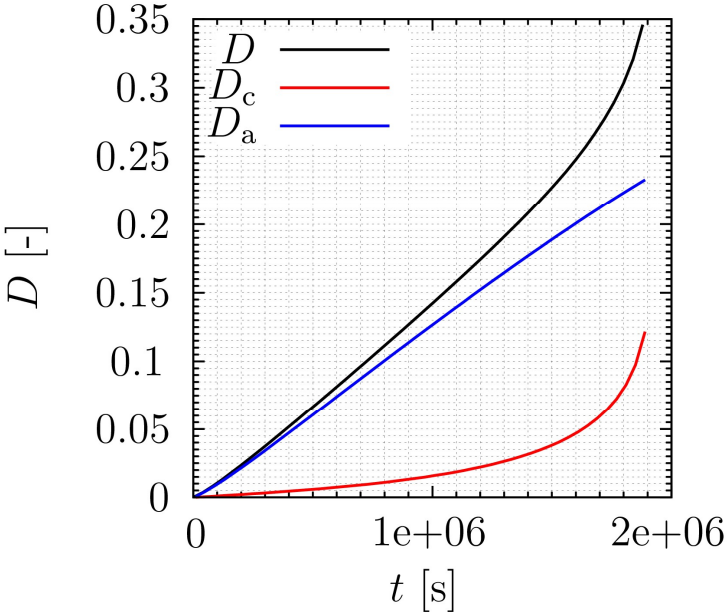
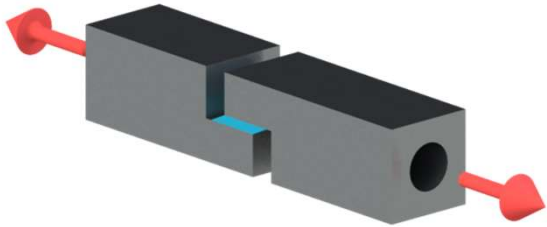
Numerical solution of the damage differential equation:

*usermat



Solution with LS-DYNA: Hygro-thermo-mechanical damage

Damage in an unsaturated sample

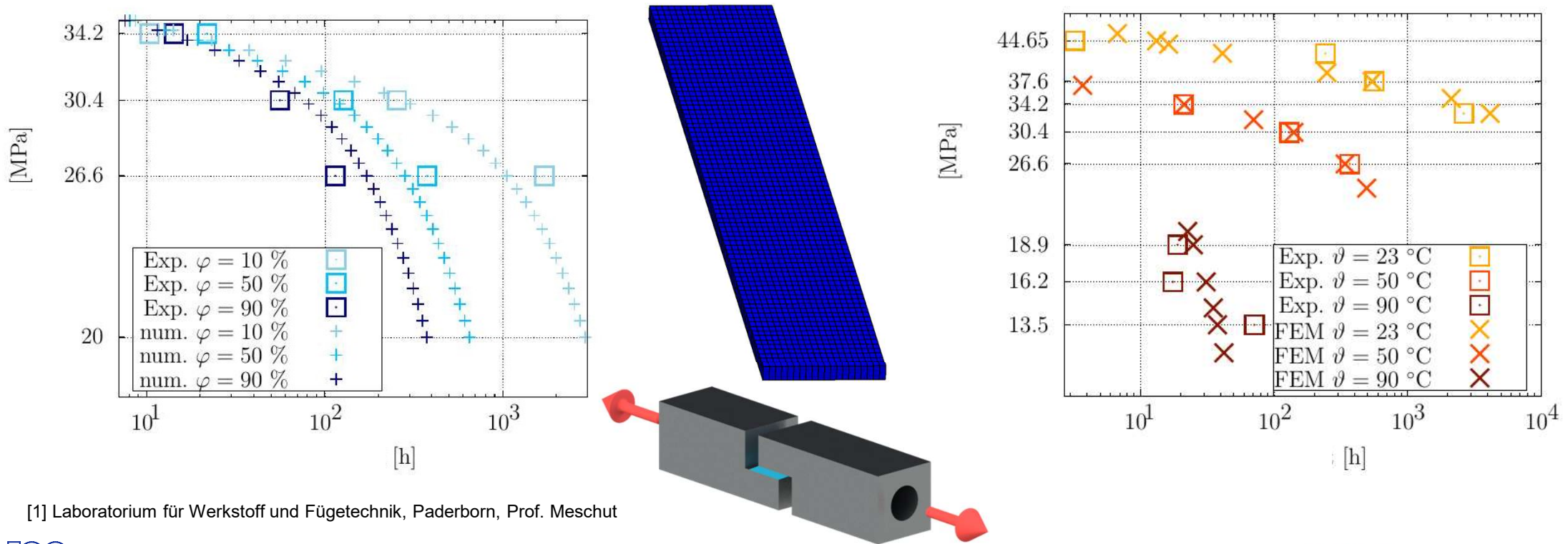


Agenda

- Motivation
- Moisture simulation with LS-DYNA
- Material model for the adhesive
 - Reversible effects
 - Irreversible damage
- Simulation and validation

FE-Calculation and lifetime prediction under hygro-thermo-mechanical influences: Verification

Tensile shear test under creep load at different temperatures and relative humidities
Comparison with experiment: good agreement



[1] Laboratorium für Werkstoff und Fügetechnik, Paderborn, Prof. Meschut

16. LS-DYNA Forum 2022

October 11 - 12, 2022, Bamberg, Germany

Fabian Kötz, Anton Matzenmiller

Method Development: Characterization, Modeling and Simulation of Hygro-Thermo Effects in Thick Layer Adhesives

Institute of Mechanics – Department of Mechanical Engineering – University of Kassel, Germany

